

# MA2S077

## Silicon epitaxial planar type

For band switching

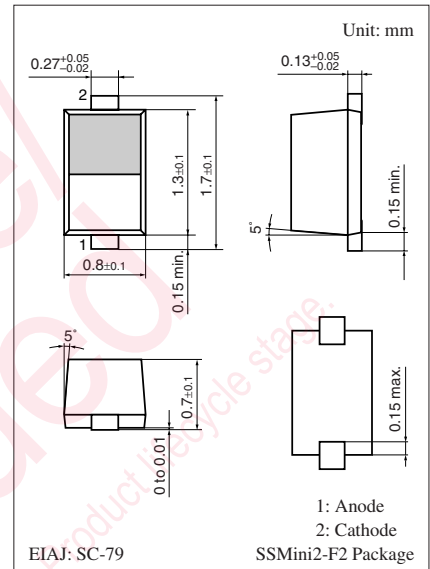
### ■ Features

- Low forward dynamic resistance  $r_f$
- Less voltage dependence of diode capacitance  $C_D$
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                       | Symbol    | Rating      | Unit             |
|---------------------------------|-----------|-------------|------------------|
| Reverse voltage                 | $V_R$     | 35          | V                |
| Forward current                 | $I_F$     | 100         | mA               |
| Operating ambient temperature * | $T_{opr}$ | -25 to +85  | $^\circ\text{C}$ |
| Storage temperature             | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

Note) \*: Maximum ambient temperature during operation.



Marking Symbol: S

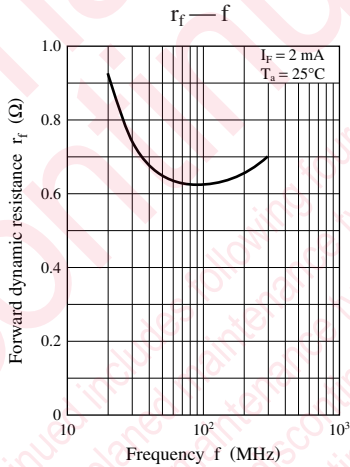
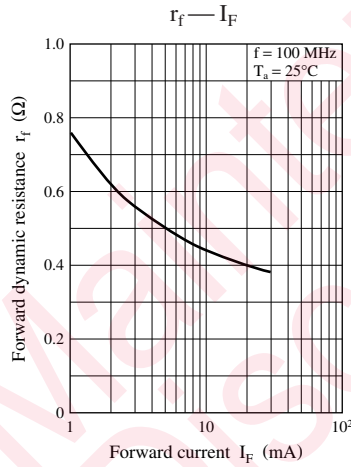
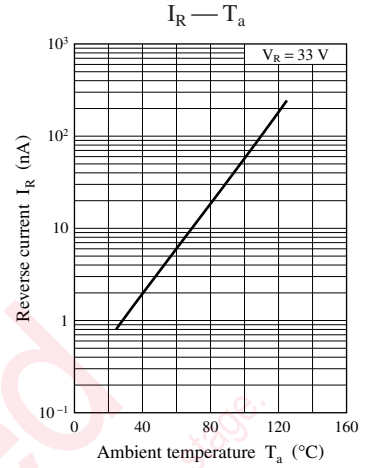
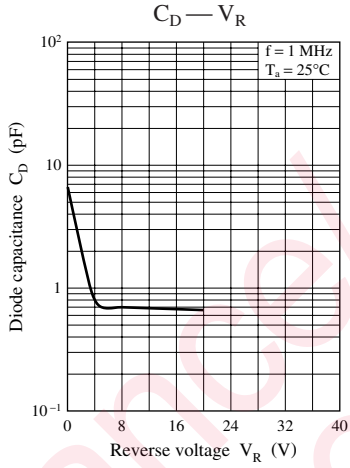
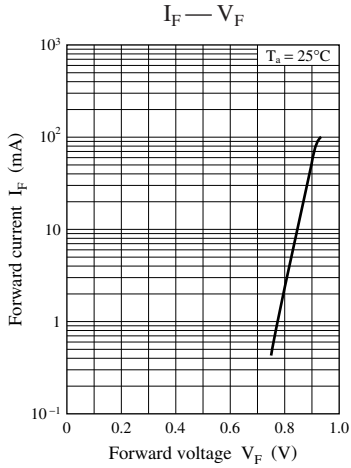
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter                    | Symbol | Conditions                                | Min | Typ  | Max    | Unit     |
|------------------------------|--------|---|-----|------|--------|----------|
| Forward voltage              | $V_F$  | $I_F = 100 \text{ mA}$                    |     | 0.92 | 1.00   | V        |
| Reverse current              | $I_R$  | $V_R = 33 \text{ V}$                      |     | 0.01 | 100.00 | nA       |
| Diode capacitance            | $C_D$  | $V_R = 6 \text{ V}, f = 1 \text{ MHz}$    |     | 0.9  | 1.2    | pF       |
| Forward dynamic resistance * | $r_f$  | $I_F = 2 \text{ mA}, f = 100 \text{ MHz}$ |     | 0.65 | 0.85   | $\Omega$ |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



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